

C. Remarks

The claims are 1-6 and 11-13, with claims 1, 11, 12 and 13 being independent. Claims 1 and 11 have been rephrased to clarify the claimed method. New claims 12 and 13 have been added. Support for the changes in claims 1 and 11 and for new claims 12 and 13 may be found, inter alia, in the specification at pages 10-16. No new matter has been added. Reconsideration of the present claims is expressly requested.

Claims 1 and 11 stand rejected under 35 U.S.C. § 102(b) as being allegedly anticipated by U.S. Patent No. U.S. Patent No. 6,586,155 B2 (Furuse '155). Claims 1 and 11 also stand rejected under 35 U.S.C. § 102(e) as being allegedly anticipated by U.S. Patent Application Publication No. 2003/0026959 A1 (Furuse '959). Claims 2-6 stand rejected under 35 U.S.C. § 103(a) as being allegedly unpatentable over Furuse '155

Prior to addressing the merits of rejection, Applicants would like to briefly review some of the key features and advantages of the presently claimed invention. That invention is directed, in part, to a method for forming an electrode and wiring. In this method, a photosensitive resin containing a water-soluble photosensitive resin component and a water-soluble metallic compound is applied onto the substrate and exposed. The exposed photosensitive resin is developed to form on the substrate a base pattern, which contains at least one water-soluble metallic compound. Subsequently, an organic metallic compound is absorbed into the base pattern, and the base pattern, in which the organic metallic compound is absorbed, is baked at a temperature of 400-600°C. Absorbing an organic metallic compound into the exposed base layer reduces the resistance of the base pattern upon baking, thereby improving the conductivity of the electrode and the wiring. As a result, the metal component of the organic metallic compound remains and is able to

make the electrode highly conductive. As recited in claim 11, this method may be used to form an electrode and a wire for an image-forming apparatus, which includes a plurality of electron-emitting devices and an image-forming member.

Furuse '155 relates to a composition for forming an electro-conductive film. Furuse teaches, for example, dissolving a photosensitive resinous component, coating the solution on the substrate, drying to evaporate the solvent, exposing the coated film, developing the exposed film and baking the remaining coated film. However, Applicants respectfully submit that Furuse '155 does not disclose or suggest a step of absorbing an organic metallic compound into the exposed base pattern containing at least a water-soluble metallic compound. Thus, Furuse '155 cannot affect the patentability of the presently claimed invention.

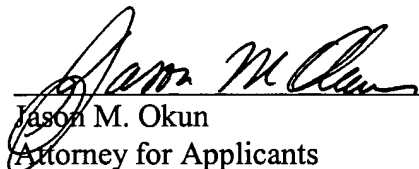
Furuse '959 is related to a method for forming a metal or a metal compound pattern by using a solution containing metal components. However, Applicants respectfully submit that Furuse '959, like Furuse '155, does not disclose or suggest a step of absorbing an organic metallic compound into the base pattern containing at least a water-soluble metallic compound. Accordingly, the presently claimed invention is patentable over Furuse '959.

Furthermore, Applicants respectfully submit that new claims 12 and 13 are patentable over the Furuse documents. Specifically, claims 12 and 13 recite a step of a step of absorbing an organic metallic compound into the precursor pattern containing at least a metallic compound. Such a step is not understood to be taught by either one of the Furuse documents.

Wherefore, Applicants respectfully request that the outstanding rejections be withdrawn and that the present case be passed to issue.

Applicants' undersigned attorney may be reached in our New York office by telephone at (212) 218-2100. All correspondence should continue to be directed to our address given below.

Respectfully submitted,



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